

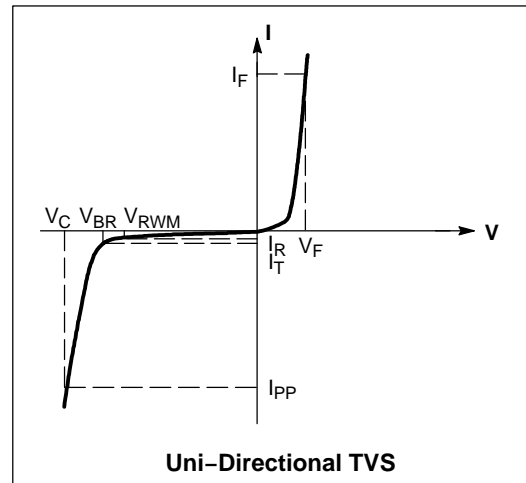


# LESD8D8.0T5G

## ELECTRICAL CHARACTERISTICS

(T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
V <sub>RWM</sub>	Working Peak Reverse Voltage
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>
I <sub>T</sub>	Test Current
I <sub>F</sub>	Forward Current
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>
P <sub>pk</sub>	Peak Power Dissipation
C	Capacitance @ V <sub>R</sub> = 0 and f = 1.0 MHz



## ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V <sub>RWM</sub>			8	V	
Breakdown Voltage	V <sub>BR</sub>	8.5		10.5	V	I <sub>R</sub> = 1mA
Peak Pulse Current (8/20μs)	I <sub>PP</sub>			25	A	
Reverse Leakage Current	I <sub>R</sub>			2	μA	V <sub>RM</sub> = 8V
Clamping Voltage	V <sub>C</sub>		10.5		V	I <sub>PP</sub> = 2 A (8 x 20μs pulse)
			16		V	I <sub>PP</sub> = 25A(8 x 20μs pulse)
ESD Clamping Voltage	V <sub>C</sub>		13		V	I <sub>PP</sub> = 16A(tp = 100ns (TLP))
Junction Capacitance	C <sub>J</sub>		150		pF	V <sub>R</sub> = 0V, f = 1MHz

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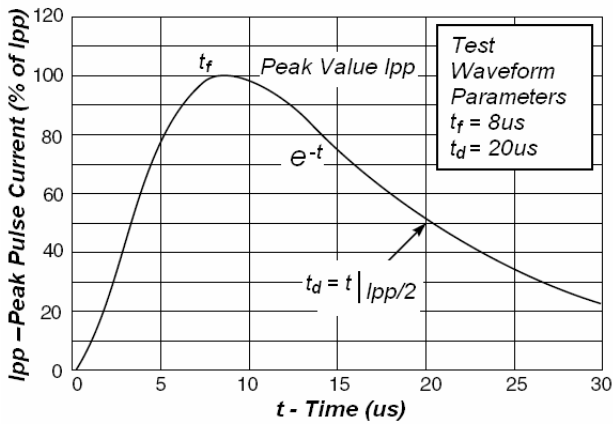


Fig1. Pulse Waveform

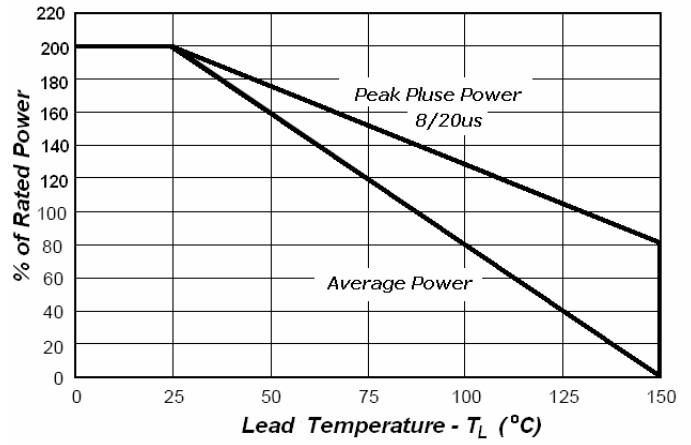


Fig2. Power Derating Curve

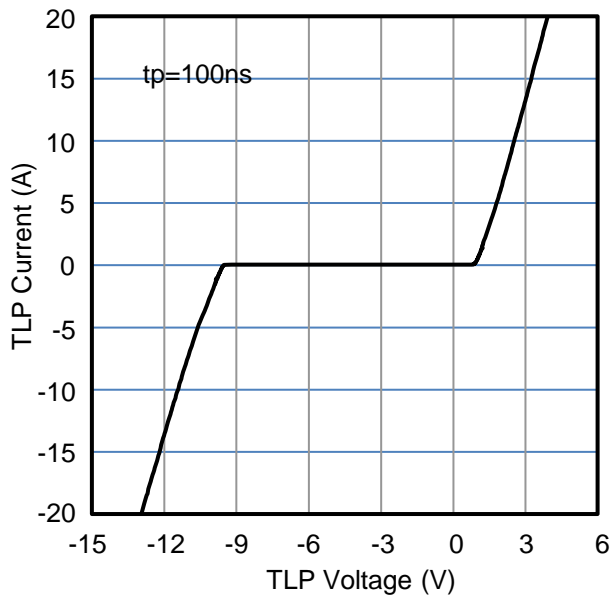


Fig3. TLP Measurement

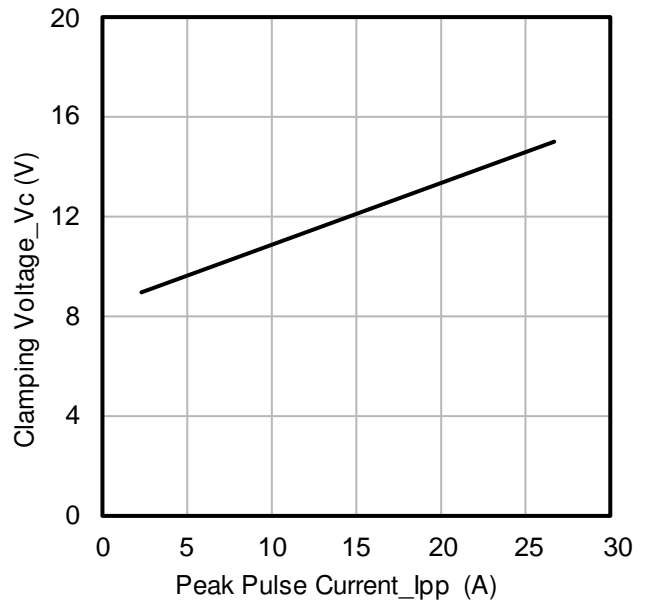
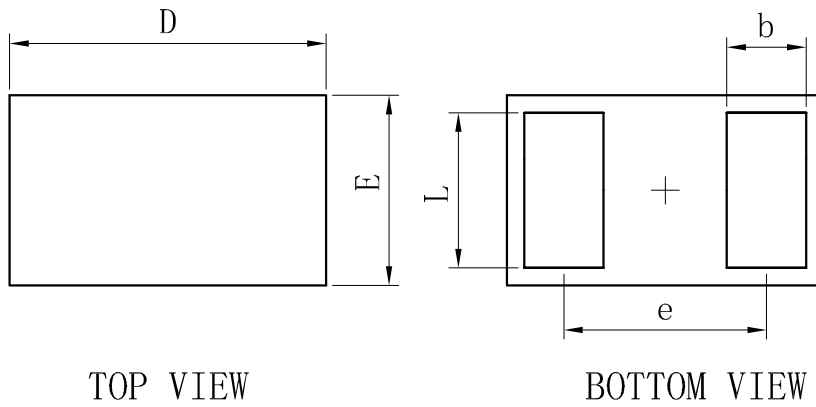


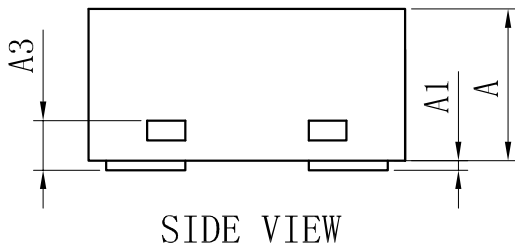
Fig4. Clamping Voltage vs. Peak Pulse Current

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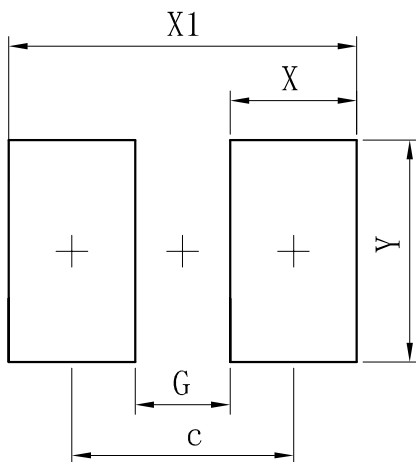
## OUTLINE AND DIMENSIONS



SOD882			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	-	0.64	-
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	-	0.05
A3	0.127REF.		
All Dimensions in mm			



## SOLDERING FOOTPRINT



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70